HP6-00002-N1-GP

Application

LGA 1155/1156 (Socket H2H)

Test result :

Item	Sample 1
Tc (℃)	58.43
Ta (℃)	32.65
P(W)	131
Rca (℃/W)	0.1964

Thermal and Mechanical Spec

Thermal performance for 130W CPU

HSK Assembly Weight: 583g

CPU Loading: 40 lbf

Safety

Component Specifications

Application System	4U Form Factor Active Solution
Material	Aluminum Fin + Copper Base + Heat pipe ø6 × 3
Dimension	88.2L × 88.2W × 112.15H mm Fin Thick=0.4mm, Pitch=1.8mm, 45 fin
Thermal interface Material	ShinEtsu 7783 (36 × 36 mm)
Fan Dimension	ø 92 × 25.4 mm
Fan Bearing Type	Two Ball
Fan Control	PWM
Rate Voltage	12V
Life Time	70,000 hrs
Speed	5000 ± 10% rpm
Airflow	90.02~100 CFM (max)
Noise	58~62 dB(A)
Connector	Lead Wire: UL1061 AWG#26
	Pin 1: black wire ------(-) Pin 2: red wire ------(+) Pin 3: yellow wire ------(F00) Pin 4: blue wire ------(PWM)
Housing	Wieson G2510C888-001 or Equivalent
Terminal	Wieson G2511-T1 or Equivalent

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.